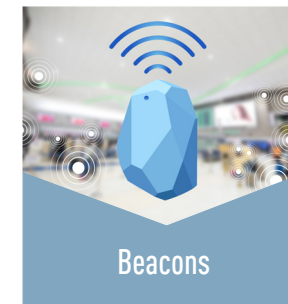


WIRELESS CONNECTIVITY

Product Leaflet

	Bluetooth® Low Energy	Bluetooth® LE & IEEE® 802.15.4		
			 NEW	
SERIES	PAN1740A	PAN1780	PAN1781	PAN4620
STATUS	Mass Production	Mass Production	Mass Production	Mass Production
PART NUMBER	ENW89852A1KF	ENW89854A1KF ENW89854A3KF (PAN1780AT)	ENW89857A1KF	ENWC9B01A1EF
RF CATEGORY	Bluetooth®5.0	Bluetooth® 5.1, IEEE® 802.15.4 & NFC-A	Bluetooth® 5.1, IEEE® 802.15.4	Bluetooth® Low Energy 4.2 & IEEE® 802.15.4
SOFTWARE & DRIVERS	SDK by Dialog	nRF5 SDK by Nordic Nordic Connect SDK	nRF5 SDK by Nordic Nordic Connect SDK	SDK by NXP
INTEGRATED CIRCUIT	DA14585	nRF52840	nRF52820	KW41Z
SIZE [MM]	9.0 x 9.5 x 1.8	15.6 x 8.7 x 2.0	15.6 x 8.7 x 2.0	15.6 x 8.7 x 1.9
RX SENSITIVITY [DBM]	-93 @ 1MB/s	-95 @ 1Mb/s -103 @ 125kb/s	-95 @ 1Mb/s -103 @ 125kb/s	BLE: -95 @ 1Mb/s 802.15.4: -100 @ 250kb/s
TX POWER (MAX.) [DBM]	+0	+8	+8	+3.5
POWER SUPPLY [V]	2.2 to 3.3	1.7 to 5.5	1.7 to 5.5	1.8 to 4.2
CURRENT CONSUMPTION	Tx: 4.9mA, 3V @ 0dBm Rx: 4.9mA, 3V	Tx: 4.8mA, 3.3V @ 0dBm Rx: 4.8mA, 3.3V	Tx: 4.9mA @ 0dBm Rx: 4.7mA	Tx: 6.1mA, 3.6V @ 0dBm Rx: 6.8mA, 3.6V
SLEEP MODE CURRENT	Sleep Mode (Full RAM Retention): 4µA Deep Sleep Mode: 520nA	Wake-on-RTC: 1.5µA Off Mode: 0.4µA	Wake-on-RTC: 1.2µA Off Mode: 0.3µA	Low Power Mode: 0.67µA
INTERFACES	GPIO, UART, SPI+, I2C, ADC, 3-axis QD	GPIO, UART, QSPI, I2C, I2S, ADC, PDM, PWM, NFC-A, USB2.0	GPIO, UART, SPI, I2C, USB2.0, QDEC	UART, SPI, I2C, ADC & DAC, TSI
MICROCONTROLLERS AND MEMORY	ARM® Cortex®-M0 96kB SRAM, 64kB OTP	ARM® Cortex®-M4F 256kB RAM, 1MB Flash	ARM® Cortex®-M4 32kB RAM, 256kB Flash	ARM® Cortex®-M0+ 128kB SRAM, 512kB Flash
OPERATING TEMP. [°C]	-40 to +85	-40 to +85	-40 to +85	-40 to +85
EVALUATION KIT	ENW89852AXKF (Dongle) ENW89852AWKF (Dongle Kit)	ENW89854AXKF (Board) ENW89854AWKF (2 Board Kit) ENW89854AZKF (AT Board) ENW89854AYKF (2 AT Board Kit)	ENW89857AXKF (Board)	ENWC9B01AQEF (Board)

Applications



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WIRELESS CONNECTIVITY

Product Leaflet

	Bluetooth® Dual Mode	Wi-Fi® & Bluetooth® LE		Wi-Fi®
			 NEW	 NEW
SERIES	PAN1326C2	PAN9026	PAN9028	PAN9520
STATUS	Mass Production	Mass Production	Mass Production	Mass Production
PART NUMBER	ENW89823A5KF	ENWF920A1EF (EU) ENWF920A1EF (US) ENWF920A1EF (CA) ENWF920A1EF (Multi-region)	ENWF9408A1EF (with PMIC) ENWF9408A2EF (without PMIC)	ENW49D01A1KF (4 MB Flash / 2 MB RAM) ENW49D02A1KF (1 MB Flash / No RAM)
RF CATEGORY	Bluetooth® 5.1 Dual Mode (BR, EDR, Bluetooth® LE)	Wi-Fi® Radio 2.4 GHz & 5.0 GHz 802.11 a/b/g/n & Bluetooth® 5.0 (BR, EDR, LE)	Wi-Fi® Radio 2.4 GHz & 5.0 GHz 802.11 a/b/g/n/ac & Bluetooth® 5.1 (BR, EDR, LE)	Wi-Fi® Embedded 802.11 b/g/n
SOFTWARE & DRIVERS	HCI Bluetooth Stack for MSP432 or STM32 Bluetooth Service Pack with Init Script	HCI Linux & i.MX RT Support MCUXpresso	HCI Linux & i.MX RT Support MCUXpresso	ESP-IDF by Espressif Arduino IDE
INTEGRATED CIRCUIT	CC2564C	88W8977	88W8987	ESP32-S2
SIZE [MM]	9.0 x 9.5 x 1.8	17.5 x 10.0 x 2.6	24.0 x 12.0 x 2.8	24.0 x 13.0 x 3.1
RX SENSITIVITY [DBM]	-90	-98 @ 1M-DSSS	-98 @ 1M-DSSS	-97 @ IEEE 802.11b
TX POWER (MAX.) [DBM]	+8	+17 @ IEEE 802.11b	+16 @ IEEE 802.11b	+19.8 @ IEEE 802.11b
POWER SUPPLY [V]	1.7 to 4.8	1.8 to 3.3	3.3 with PMIC 1.1, 1.8, 2.2, 3.3 without PMIC	3.0 to 3.6
CURRENT CONSUMPTION	Tx: 40mA, 3.3V @ 8dBm Rx: 20mA, 3.3V	Tx: 400mA @ 11Mb/s Rx: 70mA @ 11Mb/s	Tx: 320mA @ 11Mb/s Rx: 60mA @ 11Mb/s	Tx: 190mA, 3.3V @ 19.5 dBm Rx: 63mA, 3.3V @ 1 Mb/s
SLEEP MODE CURRENT	Deep Sleep Mode: 105 µA	Power Down Mode: 150µA	Power Down Mode: 150µA	Deep sleep mode <100 µA
INTERFACES	GPIO, UART, PCM	SDIO 3.0, HS UART, PCM	GPIO, SDIO 3.0, HS UART, PCM	GPIO, UART, SPI, I2C, I2S, RMT, PWM, USB, LCD, ADC & DAC
MICROCONTROLLERS AND MEMORY			88PG823 Power Management IC (PMIC)	Xtensa® 32-bit LX7 320 kB SRAM, 128 kB ROM internal memory Integrated QSPI Flash and PSRAM (size depending on version)
OPERATING TEMP. [°C]	-40 to +85	-30 to +85	-30 to +85	-40 to +85
EVALUATION KIT	ENW89819AYKF (EMK)	ENWF9201AWEF (mSDIO Dongle) ENWF9201AYEF (SDIO Dongle Kit) ENWF9201AXEF (i.MX Kit)	ENWF9408AVEF (mSD Adapter) ENWF9408AZE (i.MX Kit)	ENW49D01AZKF (Board with 4 MB Flash, 2 MB RAM)

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